10-FY12PMA025M7-P588A78
10-PY12PMA025M7-P588A78Y
10-F112PMA025M7-P588A79

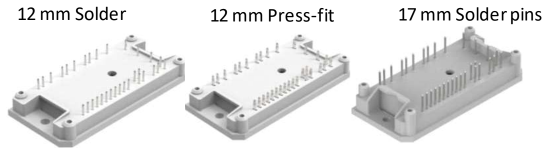
datasheet

***flow* PIM 1** — **1200 V / 25 A**

Features

- IGBT M7 with low V_{CEsat} and improved EMC behavior
- Open emitter configuration
- Compact and low inductive design
- Builtin NTC

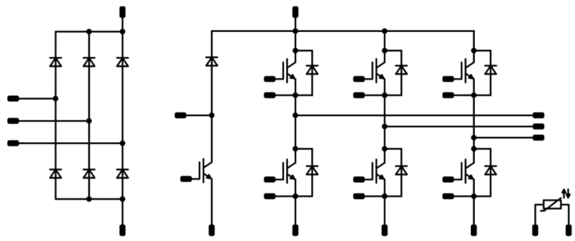
flow 1 housing



Target applications

- Industrial Drives

Schematic



Types

- 10-FY12PMA025M7-P588A78
- 10-PY12PMA025M7-P588A78Y
- 10-F112PMA025M7-P588A79

Maximum Ratings

T_j = 25 °C, unless otherwise specified

Parameter	Symbol	Condition		Value	Unit
Rectifier Diode					
Peak Repetitive Reverse Voltage	V_{RRM}			1600	V
Continuous (direct) forward current	I_F			35	A
Surge (non-repetitive) forward current	I_{FSM}	50 Hz Single Half Sine Wave t_p = 10 ms	T_j = 150 °C	270	A
Surge current capability	I^2t			370	A^2s
Total power dissipation	P_{tot}	$T_j = T_{jmax}$	T_s = 80 °C	56	W
Maximum Junction Temperature	T_{jmax}			150	°C

Maximum Ratings

T_j = 25 °C, unless otherwise specified

Parameter	Symbol	Condition	Value	Unit
Inverter Switch				
Collector-emitter voltage	V_{CES}		1200	V
Collector current	I_C		25	A
Repetitive peak collector current	I_{CRM}	t_p limited by T_{jmax}	50	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$ T_s = 80 °C	82	W
Gate-emitter voltage	V_{GES}		±20	V
Maximum junction temperature	T_{jmax}		175	°C
Inverter Diode				
Peak repetitive reverse voltage	V_{RRM}		1200	V
Continuous (direct) forward current	I_F		25	A
Repetitive peak forward current	I_{FRM}	T_j limited by T_{jmax}	50	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$ T_s = 80 °C	62	W
Maximum junction temperature	T_{jmax}		175	°C
Brake Switch				
Collector-emitter voltage	V_{CES}		1200	V
Collector current	I_C		15	A
Repetitive peak collector current	I_{CRM}	t_p limited by T_{jmax}	30	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$ T_s = 80 °C	60	W
Gate-emitter voltage	V_{GES}		±20	V
Maximum junction temperature	T_{jmax}		175	°C
Brake Diode				
Peak repetitive reverse voltage	V_{RRM}		1200	V
Continuous (direct) forward current	I_F		10	A
Repetitive peak forward current	I_{FRM}	T_j limited by T_{jmax}	20	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$ T_s = 80 °C	50	W
Maximum junction temperature	T_{jmax}		175	°C

Maximum Ratings

T_j = 25 °C, unless otherwise specified

Parameter	Symbol	Condition		Value	Unit
Module Properties					
Thermal Properties					
Storage temperature	T_{stg}			-40…+125	°C
Operation temperature under switching condition	T_{jop}			-40…(T_{jmax} - 25)	°C
Isolation Properties					
Isolation voltage	V_{isol}	DC Test Voltage*	t_p = 2 s	6000	V
		AC Voltage	t_p = 1 min	2500	V
Creepage distance		for 12 mm solder pins		min. 12,7	mm
		for 12 mm press-fit pins			
		for 17 mm solder pins			
Clearance		for 12 mm solder pins		7,91	mm
		for 12 mm press-fit pins		7,96	
		for 17 mm solder pins		min. 12,7	
Comparative Tracking Index	CTI			> 200	

*100 % tested in production

Characteristic Values

Parameter	Symbol	Conditions					Value			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_{F} [V]	I_{C} [A] I_{D} [A] I_{F} [A]	T_{j} [°C]	Min	Typ	Max	
Rectifier Diode										
Static										
Forward voltage	V_F				35	25 125		1,17 1,13		V
Reverse leakage current	I_r			1600		25			50	µA
Thermal										
Thermal resistance junction to sink	$R_{th(j-s)}$	λ_{paste} = 3,4 W/mK (PSX)						1,25		K/W

Characteristic Values

Parameter	Symbol	Conditions					Value			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	
Inverter Switch										
Static										
Gate-emitter threshold voltage	$V_{GE(th)}$	V_{CE} = 10 V			0,0025	25	5,4	6	6,6	V
Collector-emitter saturation voltage	V_{CEsat}		15		25	25 125 150		1,65 1,89 1,95	2,15	V
Collector-emitter cut-off current	I_{CES}		0	1200		25			70	µA
Gate-emitter leakage current	I_{GES}		20	0		25			500	nA
Input capacitance	C_{ies}		0	10		25		4800		pF
Output capacitance	C_{oes}		0	10		25		170		pF
Reverse transfer capacitance	C_{res}		0	10		25		57		pF
Gate charge	Q_g		15	600	25	25		180		nC
Thermal										
Thermal resistance junction to sink	$R_{th(j-s)}$	λ_{paste} = 3,4 W/mK (PSX)						1,16		K/W
Dynamic										
Turn-on delay time	$t_{d(on)}$	R_{goff} = 16 Ω R_{gon} = 16 Ω	±15	600	25	25 125 150		147 149 145		ns
Rise time	t_r	R_{goff} = 16 Ω R_{gon} = 16 Ω	±15	600	25	25 125 150		29 33 34		ns
Turn-off delay time	$t_{d(off)}$	R_{goff} = 16 Ω R_{gon} = 16 Ω	±15	600	25	25 125 150		171 191 196		ns
Fall time	t_f	R_{goff} = 16 Ω R_{gon} = 16 Ω	±15	600	25	25 125 150		95 110 115		ns
Turn-on energy (per pulse)	E_{on}	Q_{rFWD} = 2,5 µC Q_{rFWD} = 3,9 µC Q_{rFWD} = 4,3 µC	±15	600	25	25 125 150		2,06 2,66 2,82		mWs
Turn-off energy (per pulse)	E_{off}		±15	600	25	25 125 150		1,67 2,18 2,29		mWs

Characteristic Values

Parameter	Symbol	Conditions					Value			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	
Inverter Diode										
Static										
Forward voltage	V_F				25	25 125 150		1,63 1,70 1,69	2,1	V
Reverse leakage current	I_R			1200		25			35	µA
Thermal										
Thermal resistance junction to sink	$R_{th(j-s)}$	λ_{paste} = 3,4 W/mK (PSX)						1,54		K/W
Dynamic										
Peak recovery current	I_{RRM}	di/dt = 645 A/µs di/dt = 673 A/µs di/dt = 633 A/µs	±15	600	25	25 125 150		21 23 23		A
Reverse recovery time	t_{rr}					25 125 150		254 367 404		ns
Recovered charge	Q_r					25 125 150		2,54 3,88 4,28		µC
Reverse recovered energy	E_{rec}					25 125 150		0,88 1,45 1,61		mWs
Peak rate of fall of recovery current	$(di_{rf}/dt)_{max}$					25 125 150		217 134 132		A/µs

Characteristic Values

Parameter	Symbol	Conditions					Value			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	
Brake Switch										
Static										
Gate-emitter threshold voltage	$V_{GE(th)}$	V_{CE} = 10 V			0,0015	25	5,4	6	6,6	V
Collector-emitter saturation voltage	V_{CEsat}		15		15	25 125 150		1,70 1,95 2,01	2,15	V
Collector-emitter cut-off current	I_{CES}		0	1200		25			60	µA
Gate-emitter leakage current	I_{GES}		20	0		25			500	nA
Internal gate resistance	r_g							none		Ω
Input capacitance	C_{ies}		0	10		25		2900		pF
Output capacitance	C_{oes}		0	10		25		120		pF
Reverse transfer capacitance	C_{res}		0	10		25		34		pF
Gate charge	Q_g		15	600	15	25		110		nC
Thermal										
Thermal resistance junction to sink	$R_{th(j-s)}$	λ_{paste} = 3,4 W/mK (PSX)						1,60		K/W
Dynamic										
Turn-on delay time	$t_{d(on)}$	R_{goff} = 32 Ω R_{gon} = 32 Ω	15/0	700	15	25 125 150		293 257 246		ns
Rise time	t_r	R_{goff} = 32 Ω R_{gon} = 32 Ω	15/0	700	15	25 125 150		185 200 203		ns
Turn-off delay time	$t_{d(off)}$	R_{goff} = 32 Ω R_{gon} = 32 Ω	15/0	700	15	25 125 150		398 442 450		ns
Fall time	t_f	R_{goff} = 32 Ω R_{gon} = 32 Ω	15/0	700	15	25 125 150		66 88 92		ns
Turn-on energy (per pulse)	E_{on}	Q_{rFWD} = 1,1 µC Q_{rFWD} = 1,9 µC Q_{rFWD} = 2,1 µC	15/0	700	15	25 125 150		2,95 3,57 3,74		mWs
Turn-off energy (per pulse)	E_{off}		15/0	700	15	25 125 150		1,33 1,71 1,81		mWs

Characteristic Values

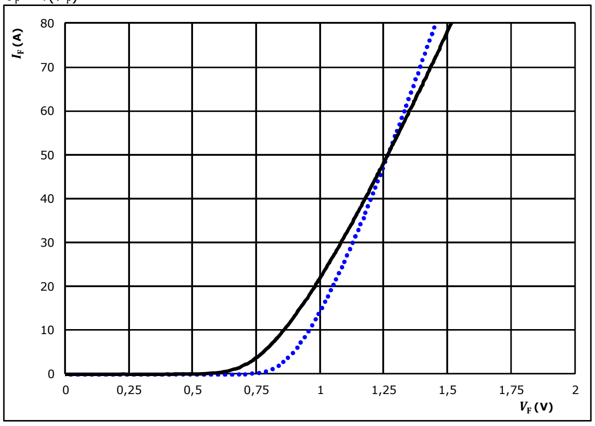
Parameter	Symbol	Conditions					Value			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_{F} [V]	I_{C} [A] I_{D} [A] I_{F} [A]	T_{j} [°C]	Min	Typ	Max	
Brake Diode										
Static										
Forward voltage	V_{F}				10	25 125 150		1,61 1,69 1,69	2,1	V
Reverse leakage current	I_{R}			1200		25			25	µA
Thermal										
Thermal resistance junction to sink	$R_{th(j-s)}$	λ_{paste} = 3,4 W/mK (PSX)						1,91		K/W
Dynamic										
Peak recovery current	I_{RRM}	di/dt = 69 A/µs di/dt = 69 A/µs di/dt = 67 A/µs	15/0	700	15	25 125 150		6 7 7		A
Reverse recovery time	t_{rr}					25 125 150		295 485 544		ns
Recovered charge	Q_{r}					25 125 150		1,140 1,882 2,120		µC
Reverse recovered energy	E_{rec}					25 125 150		0,422 0,781 0,895		mWs
Peak rate of fall of recovery current	$(di_{rf}/dt)_{max}$					25 125 150		44 29 25		A/µs
Thermistor										
Rated resistance	R					25		22		kΩ
Deviation of R_{100}	$\Delta_{R/R}$	R_{100} = 1484 Ω				100	-5		5	%
Power dissipation	P					25		5		mW
Power dissipation constant						25		1,5		mW/K
B-value	$B_{(25/50)}$	Tol. ±1 %				25		3962		K
B-value	$B_{(25/100)}$	Tol. ±1 %				25		4000		K
Vincotech NTC Reference									I	

Rectifier Diode Characteristics

figure 1. **Rectifier Diode**

Typical forward characteristics

$I_F = f(V_F)$



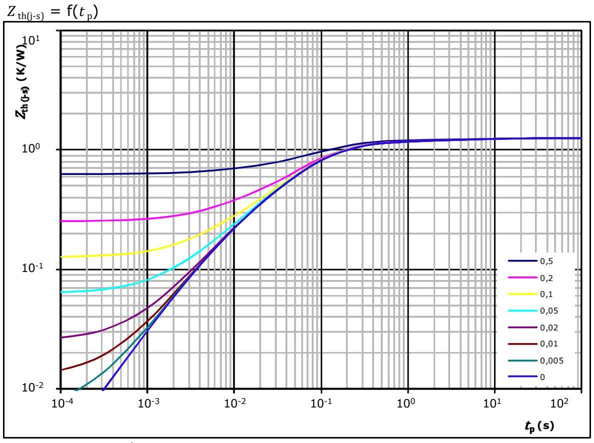
t_p = 250 µs

T_j: 25 °C (dotted)
125 °C (solid)

figure 2. **Rectifier Diode**

Transient thermal impedance as a function of pulse width

$Z_{th(j-s)} = f(t_p)$



$D = t_p / T$

$R_{th(j-s)}$ = 1,25 K/W

Diode thermal model values

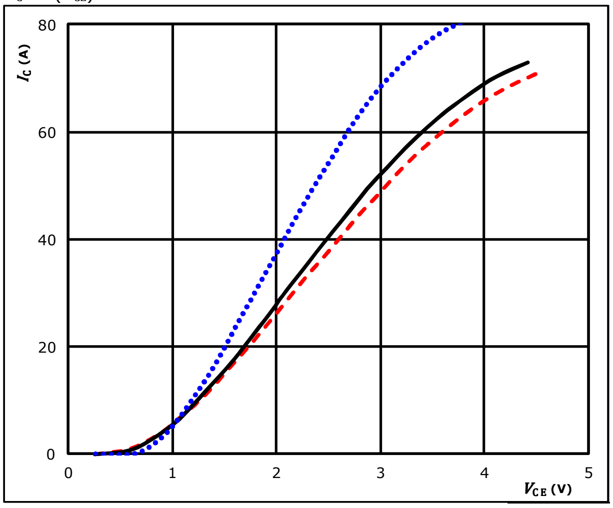
R (K/W)	τ (s)
8,00E-02	5,22E+00
1,56E-01	4,18E-01
6,95E-01	8,82E-02
2,23E-01	3,07E-02
9,97E-02	5,99E-03

Inverter Switch Characteristics

figure 1. **IGBT**

Typical output characteristics

$I_C = f(V_{CE})$

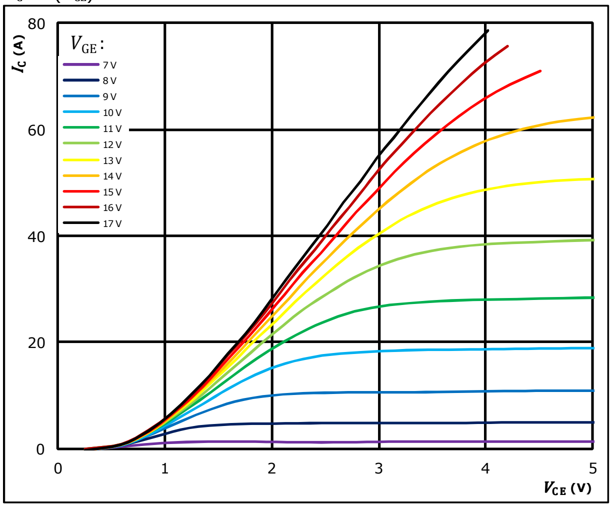


t_p =	250	μs		25 °C	···········
V_{GE} =	15	V	T_j:	125 °C	———
				150 °C	– – –

figure 2. **IGBT**

Typical output characteristics

$I_C = f(V_{CE})$



t_p = 250 μs

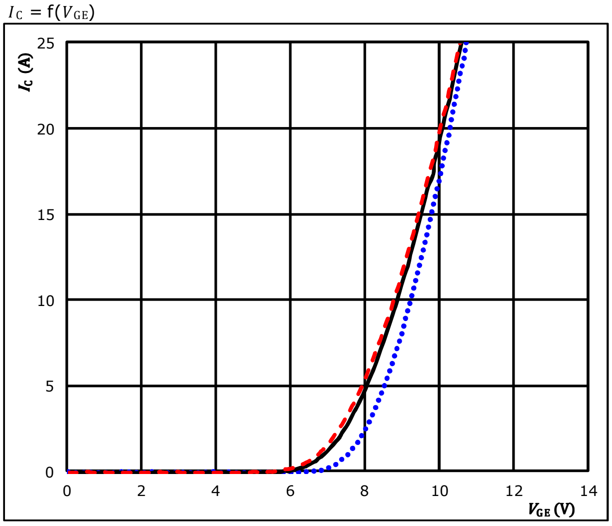
T_j = 125 °C

V_{GE} from 7 V to 17 V in steps of 1 V

figure 3. **IGBT**

Typical transfer characteristics

$I_C = f(V_{GE})$

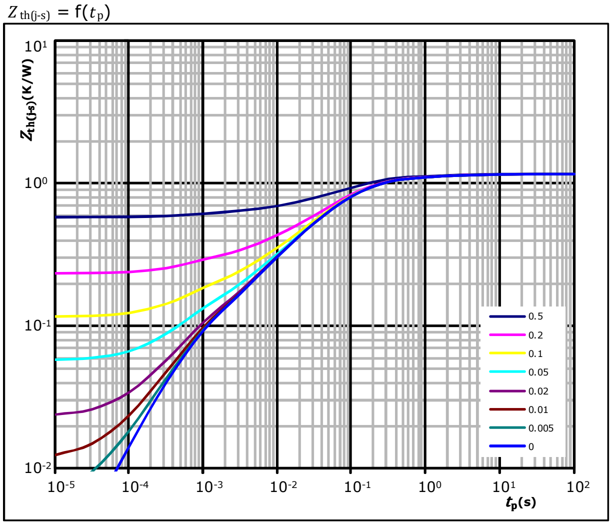


t_p =	100	μs		25 °C	···········
V_{CE} =	10	V	T_j:	125 °C	———
				150 °C	– – –

figure 4. **IGBT**

Transient thermal impedance as function of pulse duration

$Z_{th(j\text{-}s)} = f(t_p)$



D = t_p / T

$R_{th(j\text{-}s)}$ = 1,16 K/W

IGBT thermal model values

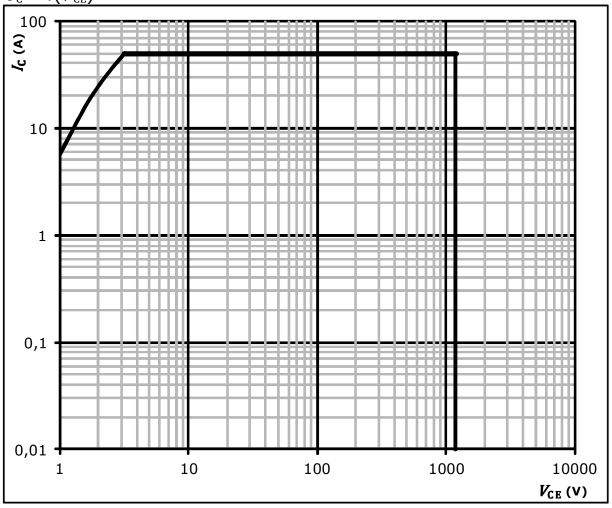
R (K/W)	τ (s)
5,33E-02	3,54E+00
1,07E-01	5,75E-01
5,05E-01	1,04E-01
2,68E-01	3,30E-02
1,51E-01	7,35E-03
7,80E-02	6,52E-04

Inverter Switch Characteristics

figure 5.	IGBT

Safe operating area

$I_C = f(V_{CE})$



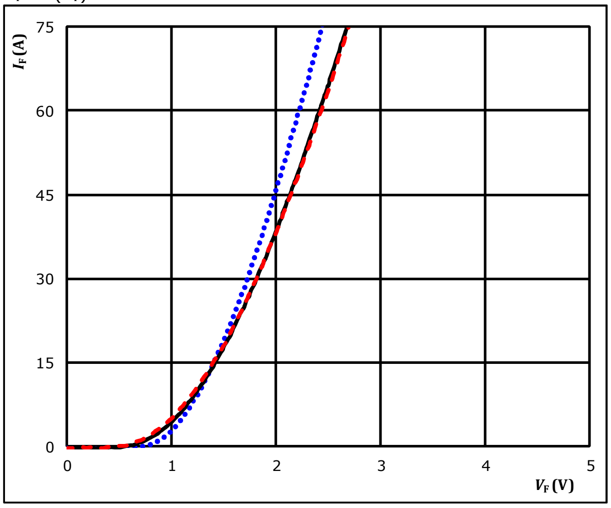
D =	single pulse	
T_s =	80	ºC
V_{GE} =	±15	V
T_j =	T_{jmax}	

Inverter Diode Characteristics

figure 1. **FWD**

Typical forward characteristics

$I_F = f(V_F)$



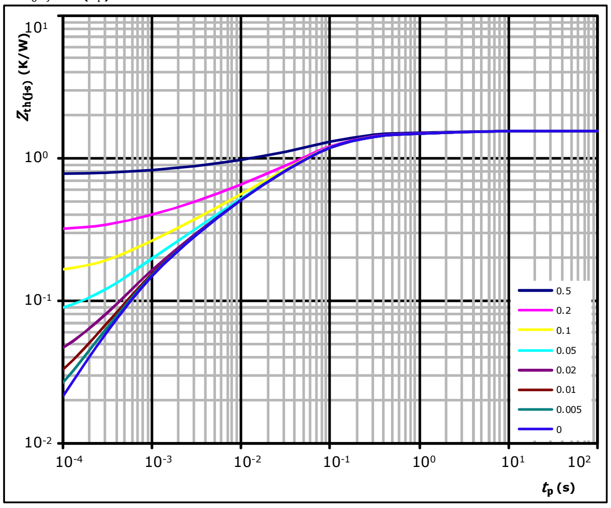
t_p = 250 µs

T_j: 25 °C; 125 °C; 150 °C

figure 2. **FWD**

Transient thermal impedance as a function of pulse width

$Z_{th(j-s)} = f(t_p)$



$D = t_p / T$

$R_{th(j-s)}$ = 1,54 K/W

FWD thermal model values

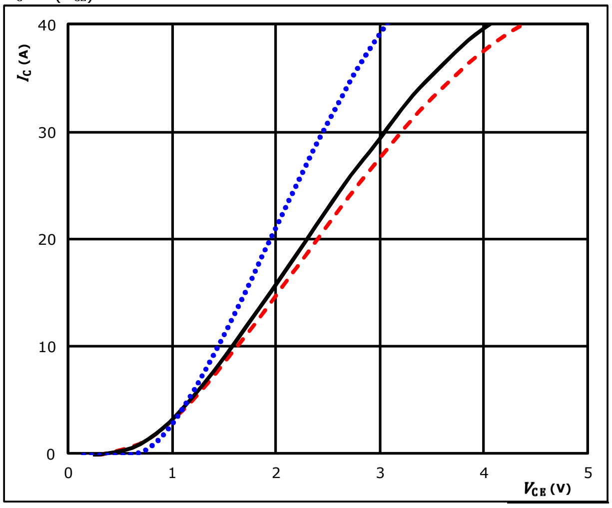
R (K/W)	τ (s)
4,69E-02	5,05E+00
1,06E-01	7,09E-01
5,57E-01	1,01E-01
4,68E-01	3,22E-02
2,35E-01	5,52E-03
8,77E-02	1,01E-03
4,01E-02	5,52E-04

Brake Switch Characteristics

figure 1. IGBT

Typical output characteristics

$I_C = f(V_{CE})$

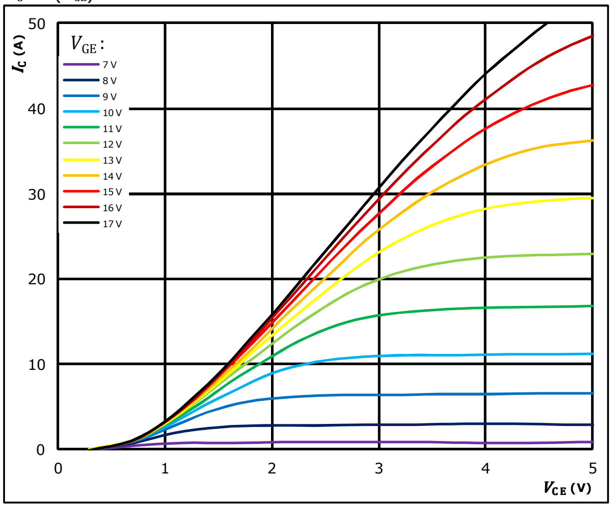


t_p =	250	µs		25	°C
V_{GE} =	15	V	T_j:	125	°C
				150	°C

figure 2. IGBT

Typical output characteristics

$I_C = f(V_{CE})$

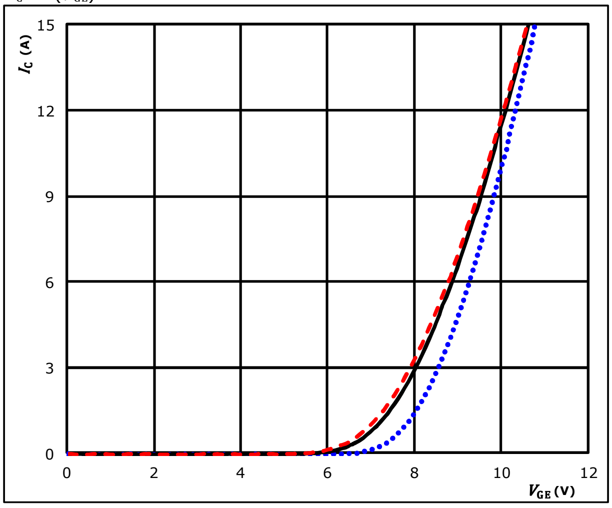


t_p =	250	µs
T_j =	150	°C
V_{GE} from	7 V to 17 V in steps of 1 V	

figure 3. IGBT

Typical transfer characteristics

$I_C = f(V_{GE})$

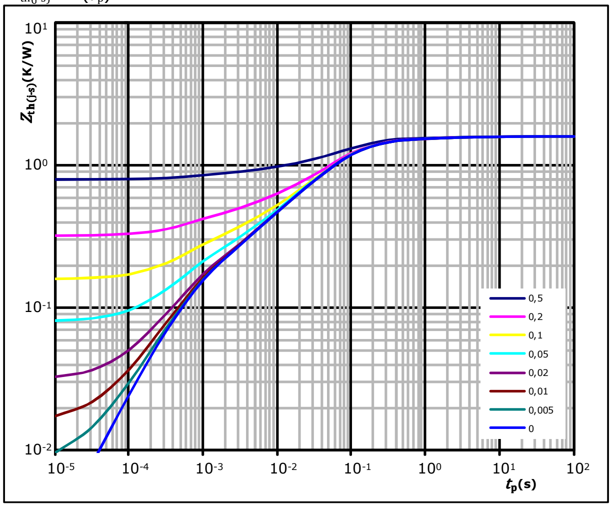


t_p =	100	µs		25	°C
V_{CE} =	10	V	T_j:	125	°C
				150	°C

figure 4. IGBT

Transient thermal impedance as function of pulse duration

$Z_{th(j\text{-}s)} = f(t_p)$



D = t_p / T

$R_{th(j\text{-}s)}$ = 1,60 K/W

IGBT thermal model values

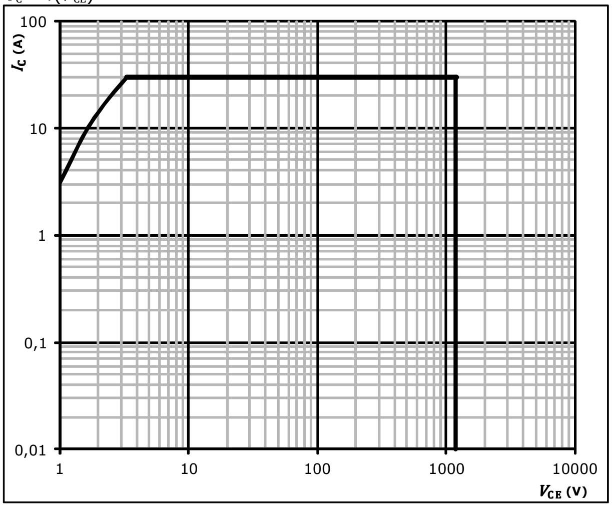
R (K/W)	τ (s)
4,90E-02	4,40E+00
1,40E-01	5,34E-01
8,04E-01	8,02E-02
2,98E-01	2,57E-02
1,69E-01	5,09E-03
1,35E-01	6,41E-04

Brake Switch Characteristics

figure 5.	IGBT

Safe operating area

$I_C = f(V_{CE})$



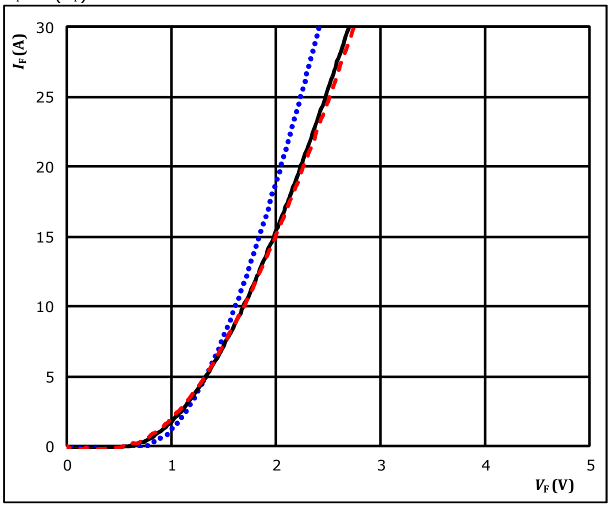
D =	single pulse	
T_s =	80	ºC
V_{GE} =	±15	V
T_j =	T_{jmax}	

Brake Diode Characteristics

figure 1. **FWD**

Typical forward characteristics

$I_F = f(V_F)$



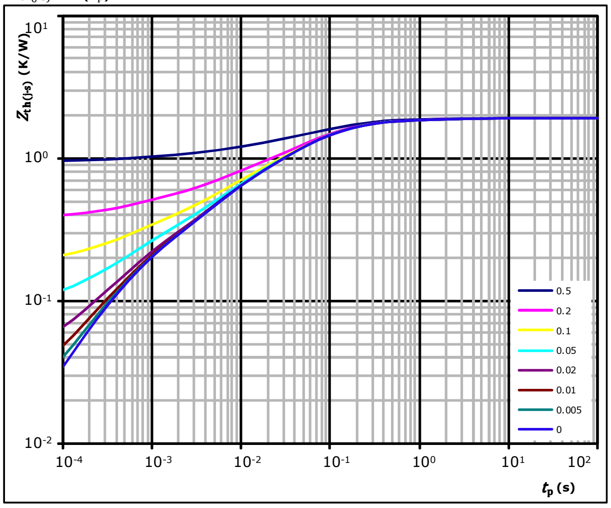
t_p = 250 μs

T_j: 25 °C; 125 °C; 150 °C

figure 2. **FWD**

Transient thermal impedance as a function of pulse width

$Z_{th(j-s)} = f(t_p)$



$D = t_p / T$

$R_{th(j-s)}$ = 1,91 K/W

FWD thermal model values

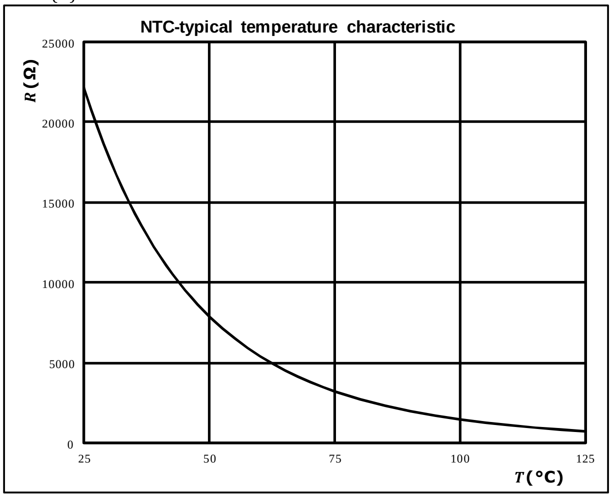
R (K/W)	τ (s)
9,38E-02	2,25E+00
3,43E-01	2,12E-01
8,53E-01	5,82E-02
3,59E-01	9,80E-03
1,37E-01	2,88E-03
1,26E-01	4,78E-04

Thermistor Characteristics

figure 1. **Thermistor**

Typical NTC characteristic as a function of temperature

$R = f(T)$

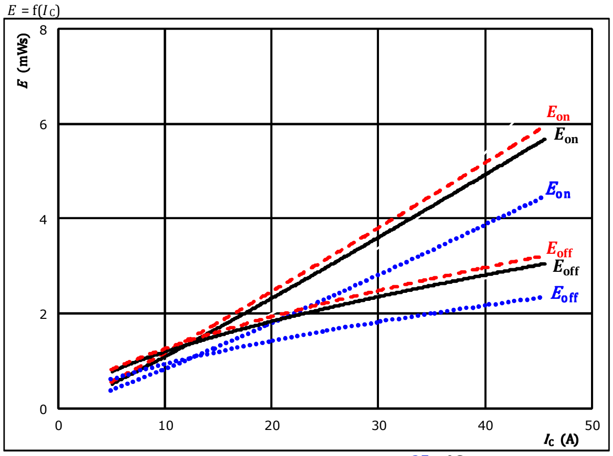


Inverter Switching Characteristics

figure 1. IGBT

Typical switching energy losses as a function of collector current

$E = f(I_C)$



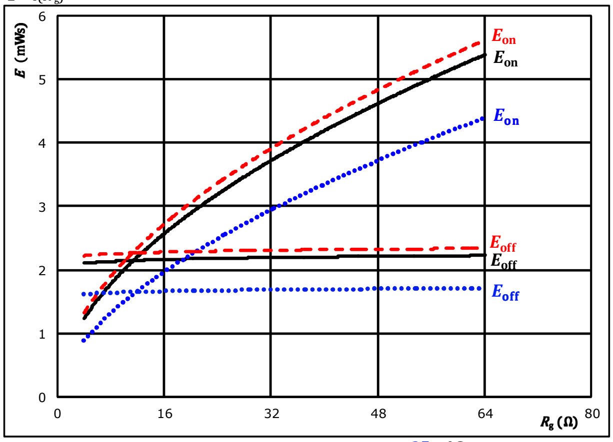
With an inductive load at

V_{CE} =	600	V	T_j:	25	°C	dotted
V_{GE} =	±15	V		125	°C	solid
R_{gon} =	16	Ω		150	°C	dashed
R_{goff} =	16	Ω				

figure 2. IGBT

Typical switching energy losses as a function of gate resistor

$E = f(R_g)$



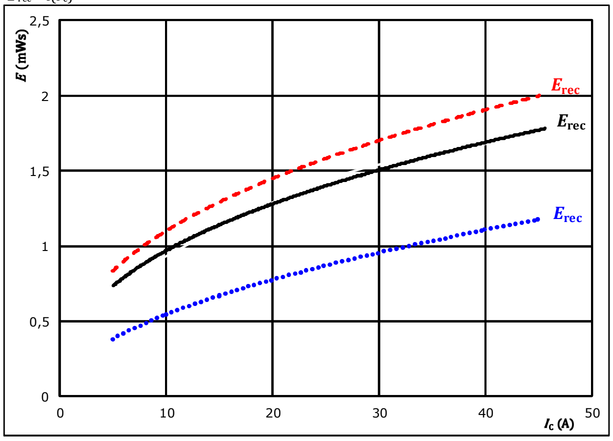
With an inductive load at

V_{CE} =	600	V	T_j:	25	°C	dotted
V_{GE} =	±15	V		125	°C	solid
I_C =	25	A		150	°C	dashed

figure 3. FWD

Typical reverse recovered energy loss as a function of collector current

$E_{rec} = f(I_c)$



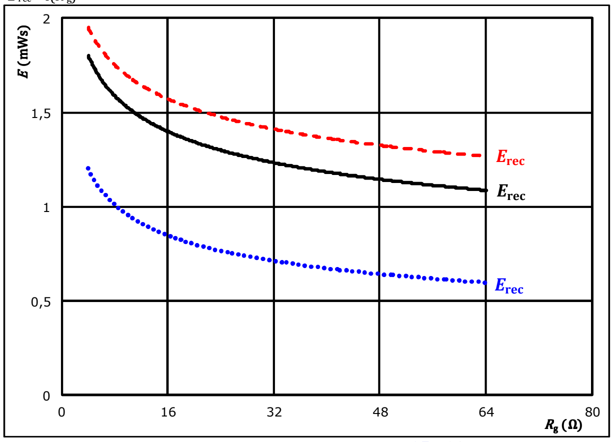
With an inductive load at

V_{CE} =	600	V	T_j:	25	°C	dotted
V_{GE} =	±15	V		125	°C	solid
R_{gon} =	16	Ω		150	°C	dashed

figure 4. FWD

Typical reverse recovered energy loss as a function of gate resistor

$E_{rec} = f(R_g)$



With an inductive load at

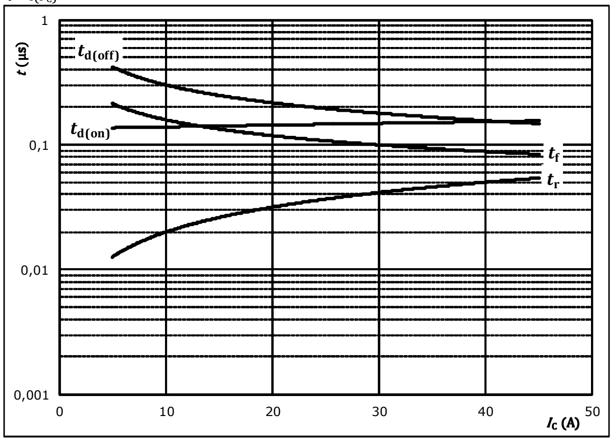
V_{CE} =	600	V	T_j:	25	°C	dotted
V_{GE} =	±15	V		125	°C	solid
I_C =	25	A		150	°C	dashed

Inverter Switching Characteristics

figure 5. IGBT

Typical switching times as a function of collector current

$t = f(I_C)$



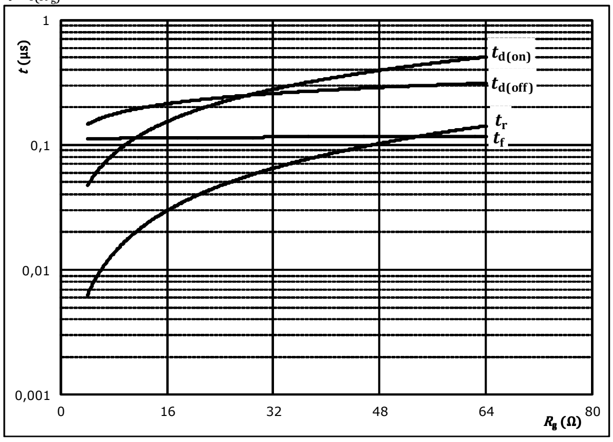
With an inductive load at

T_j =	150	°C
V_{CE} =	600	V
V_{GE} =	±15	V
R_{gon} =	16	Ω
R_{goff} =	16	Ω

figure 6. IGBT

Typical switching times as a function of gate resistor

$t = f(R_g)$



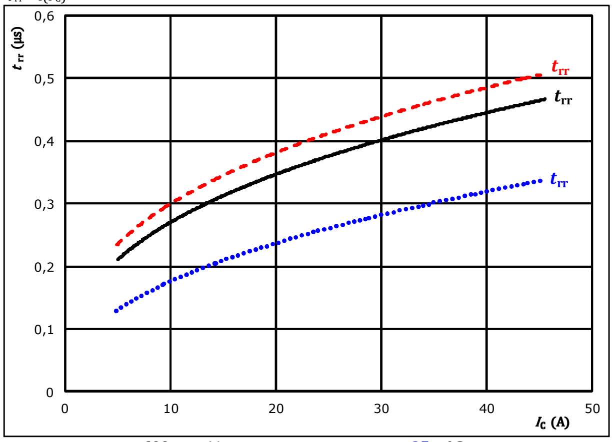
With an inductive load at

T_j =	150	°C
V_{CE} =	600	V
V_{GE} =	±15	V
I_C =	25	A

figure 7. FWD

Typical reverse recovery time as a function of collector current

$t_{rr} = f(I_C)$

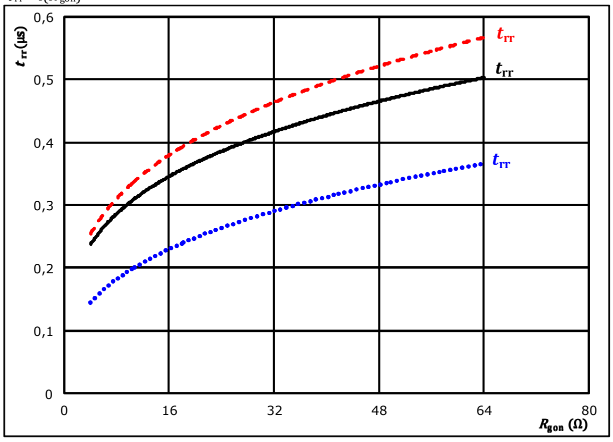


At					
V_{CE} =	600	V		25 °C	dotted
V_{GE} =	±15	V	T_j:	125 °C	solid
R_{gon} =	16	Ω		150 °C	dashed

figure 8. FWD

Typical reverse recovery time as a function of IGBT turn on gate resistor

$t_{rr} = f(R_{gon})$



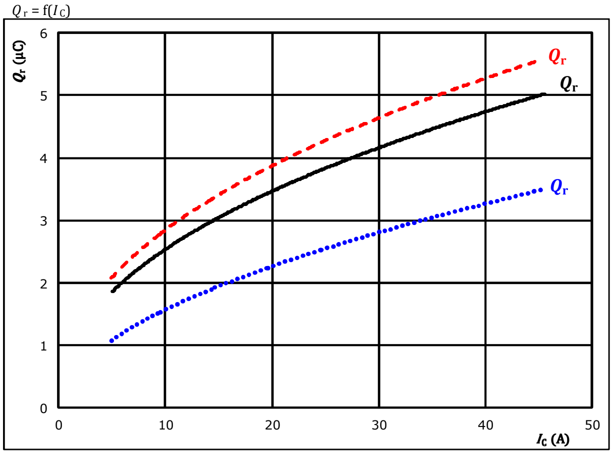
At					
V_{CE} =	600	V		25 °C	dotted
V_{GE} =	±15	V	T_j:	125 °C	solid
I_C =	25	A		150 °C	dashed

Inverter Switching Characteristics

figure 9. **FWD**

Typical recovered charge as a function of collector current

$Q_r = f(I_C)$

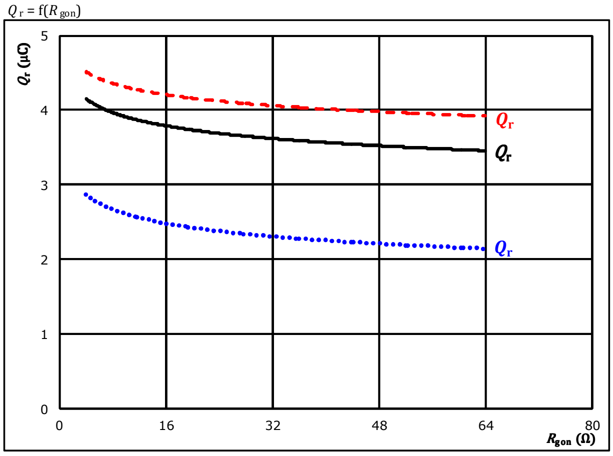


At					
V_{CE} =	600	V		25 °C	············
V_{GE} =	±15	V	T_j:	125 °C	———
R_{gon} =	16	Ω		150 °C	– – –

figure 10. **FWD**

Typical recovered charge as a function of IGBT turn on gate resistor

$Q_r = f(R_{gon})$

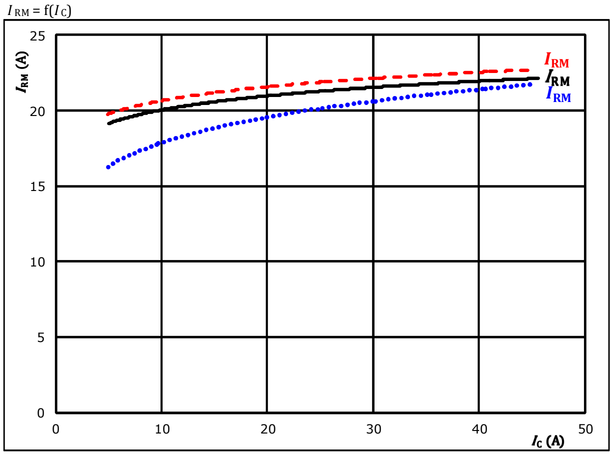


At					
V_{CE}=	600	V		25 °C	············
V_{GE} =	±15	V	T_j:	125 °C	———
I_C=	25	A		150 °C	– – –

figure 11. **FWD**

Typical peak reverse recovery current current as a function of collector current

$I_{RM} = f(I_C)$

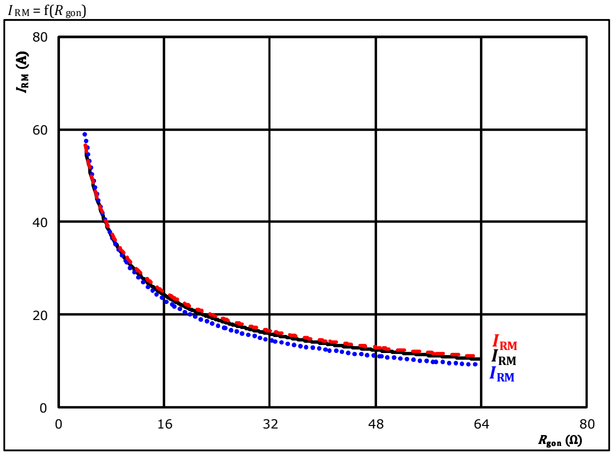


At					
V_{CE}:	600	V		25 °C	············
V_{GE} =	±15	V	T_j:	125 °C	———
R_{gon} =	16	Ω		150 °C	– – –

figure 12. **FWD**

Typical peak reverse recovery current as a function of IGBT turn on gate resistor

$I_{RM} = f(R_{gon})$



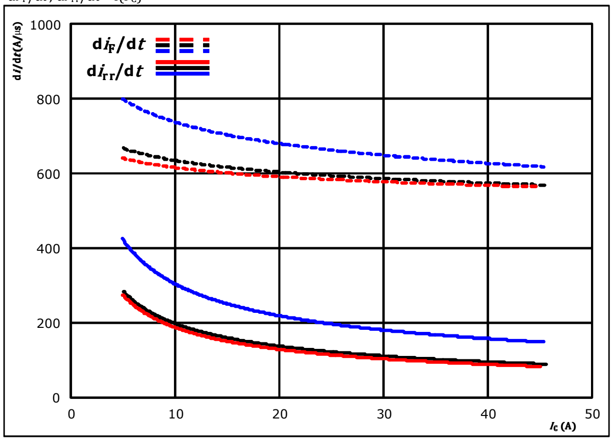
At					
V_{CE} =	600	V		25 °C	············
V_{GE} =	±15	V	T_j:	125 °C	———
I_C =	25	A		150 °C	– – –

Inverter Switching Characteristics

figure 13. FWD

Typical rate of fall of forward and reverse recovery current as a function of collector current

di_F/dt, $di_{rr}/dt = f(I_C)$

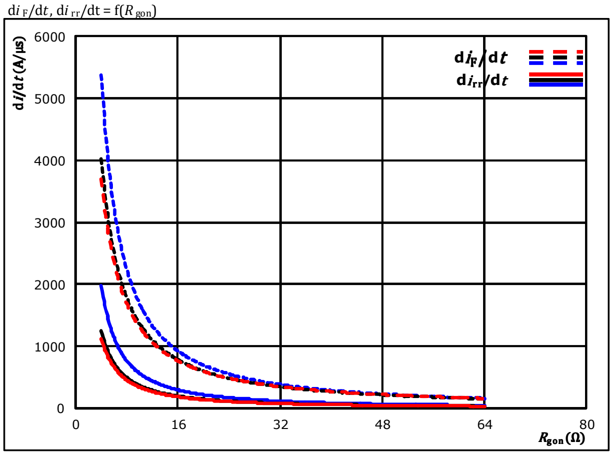


At						
V_{CE} =	600	V	T_j:	25	°C	dotted
V_{GE} =	±15	V		125	°C	solid
R_{gon} =	16	Ω		150	°C	dashed

figure 14. FWD

Typical rate of fall of forward and reverse recovery current as a function of IGBT turn on gate resistor

di_F/dt, $di_{rr}/dt = f(R_{gon})$

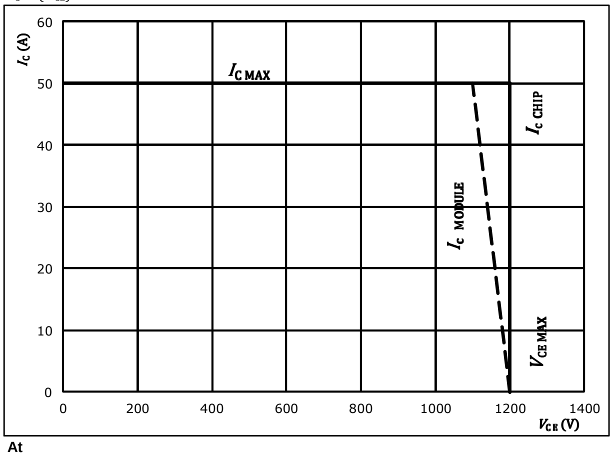


At						
V_{CE} =	600	V	T_j:	25	°C	dotted
V_{GE} =	±15	V		125	°C	solid
I_C=	25	A		150	°C	dashed

figure 15. IGBT

Reverse bias safe operating area

$I_C = f(V_{CE})$



At		
T_j =	175	°C
R_{gon} =	16	Ω
R_{goff} =	16	Ω

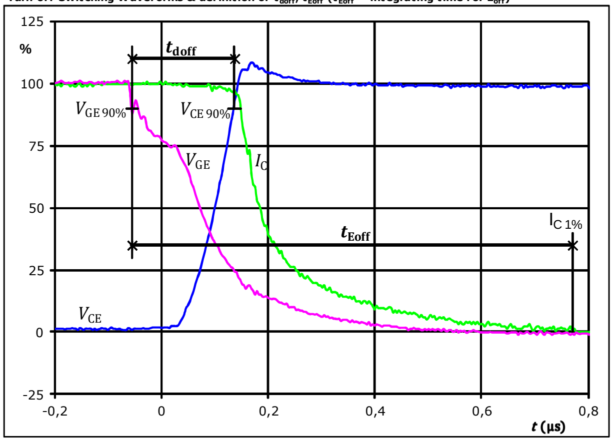
Inverter Switching Definitions

General conditions

T_j	=	125 °C
R_{gon}	=	16 Ω
R_{goff}	=	16 Ω

figure 1. **IGBT**

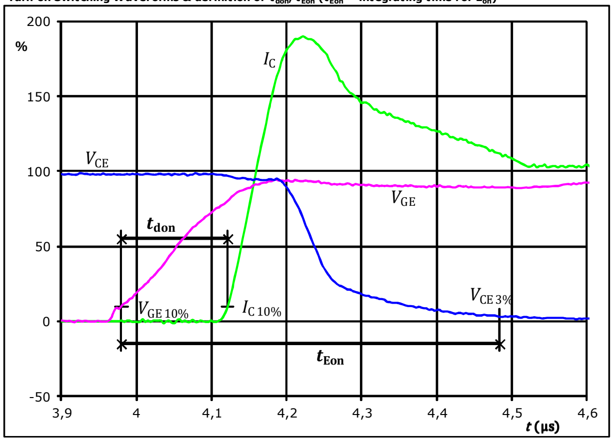
Turn-off Switching Waveforms & definition of t_{doff}, t_{Eoff} (t_{Eoff} = integrating time for E_{off})



$V_{GE}(0\%)$ =	-15	V
$V_{GE}(100\%)$ =	15	V
$V_C(100\%)$ =	600	V
$I_C(100\%)$ =	25	A
t_{doff} =	0,191	µs
t_{Eoff} =	0,826	µs

figure 2. **IGBT**

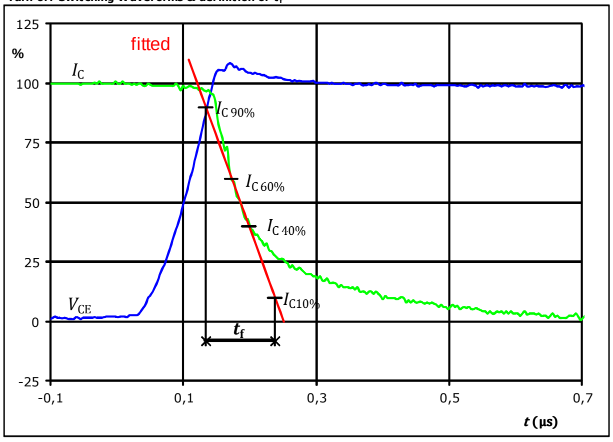
Turn-on Switching Waveforms & definition of t_{don}, t_{Eon} (t_{Eon} = integrating time for E_{on})



$V_{GE}(0\%)$ =	-15	V
$V_{GE}(100\%)$ =	15	V
$V_C(100\%)$ =	600	V
$I_C(100\%)$ =	25	A
t_{don} =	0,149	µs
t_{Eon} =	0,504	µs

figure 3. **IGBT**

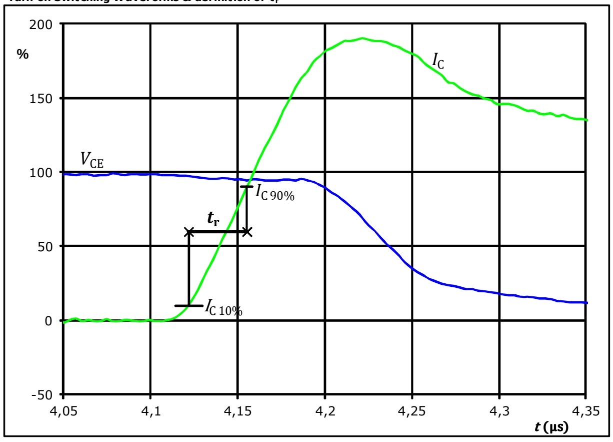
Turn-off Switching Waveforms & definition of t_f



$V_C(100\%)$ =	600	V
$I_C(100\%)$ =	25	A
t_f =	0,110	µs

figure 4. **IGBT**

Turn-on Switching Waveforms & definition of t_r

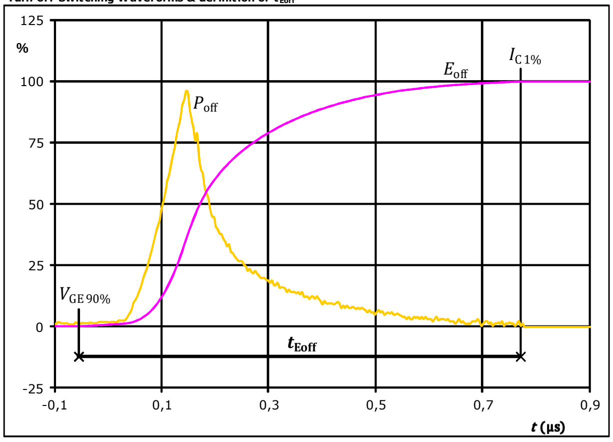


$V_C(100\%)$ =	600	V
$I_C(100\%)$ =	25	A
t_r =	0,033	µs

Inverter Switching Characteristics

figure 5. IGBT

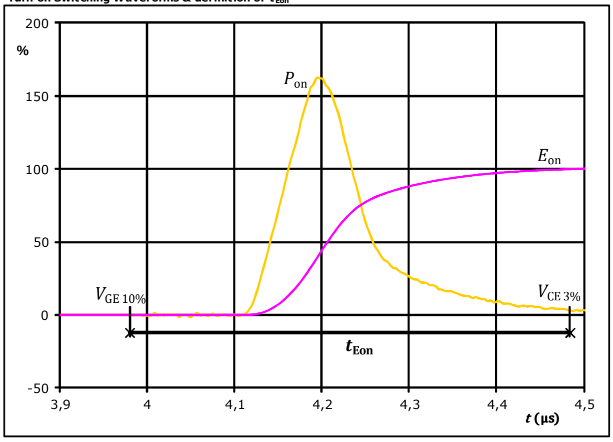
Turn-off Switching Waveforms & definition of t_{Eoff}



P_{off} (100%) =	15,13	kW
E_{off} (100%) =	2,18	mJ
t_{Eoff} =	0,83	µs

figure 6. IGBT

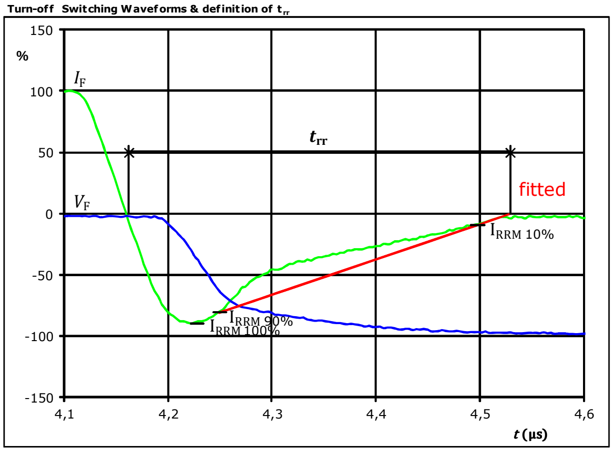
Turn-on Switching Waveforms & definition of t_{Eon}



P_{on} (100%) =	15,13	kW
E_{on} (100%) =	2,66	mJ
t_{Eon} =	0,50	µs

figure 7. FWD

Turn-off Switching Waveforms & definition of t_{rr}

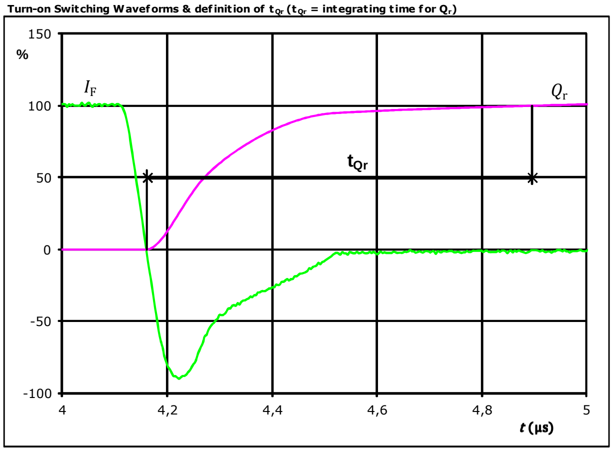


V_F (100%) =	600	V
I_F (100%) =	25	A
I_{RRM} (100%) =	-23	A
t_{rr} =	0,367	µs

Inverter Switching Characteristics

figure 8. FWD

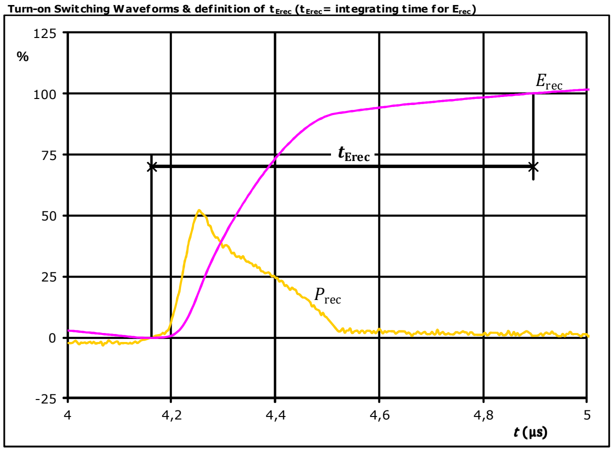
Turn-on Switching Waveforms & definition of t_{Qr} (t_{Qr} = integrating time for Q_r)



I_F (100%) =	25	A
Q_r (100%) =	3,88	µC
t_{Qr} =	0,73	µs

figure 9. FWD

Turn-on Switching Waveforms & definition of t_{Erec} (t_{Erec} = integrating time for E_{rec})



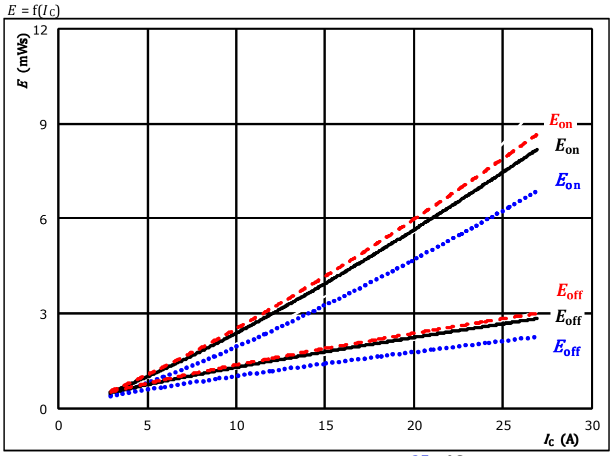
P_{rec} (100%) =	15,13	kW
E_{rec} (100%) =	1,45	mJ
t_{Erec} =	0,73	µs

Brake Switching Characteristics

figure 1. **IGBT**

Typical switching energy losses as a function of collector current

$E = f(I_C)$



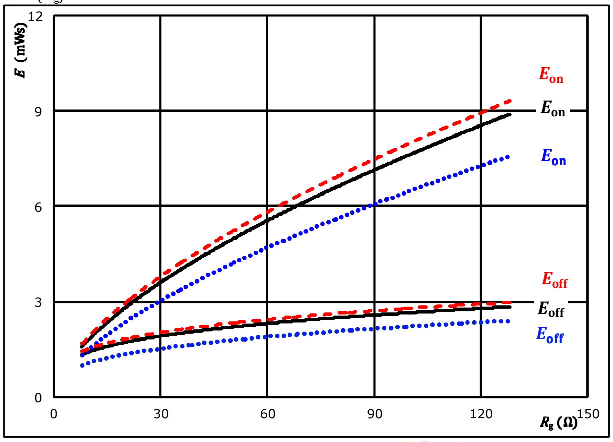
With an inductive load at

V_{CE} =	700	V	T_j:	25 °C	dotted
V_{GE} =	15/0	V		125 °C	solid
R_{gon} =	32	Ω		150 °C	dashed
R_{goff} =	32	Ω			

figure 2. **IGBT**

Typical switching energy losses as a function of gate resistor

$E = f(R_g)$



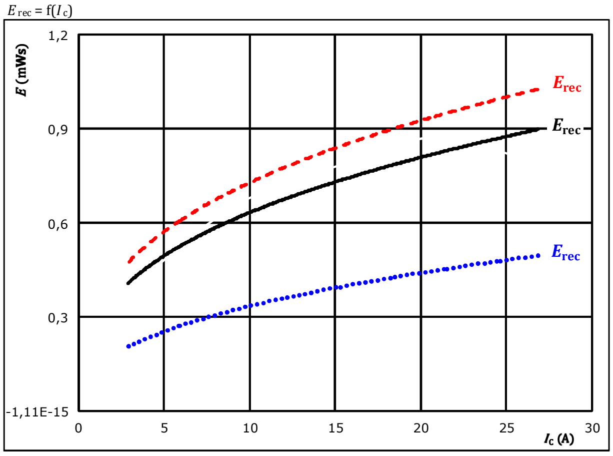
With an inductive load at

V_{CE} =	700	V	T_j:	25 °C	dotted
V_{GE} =	15/0	V		125 °C	solid
I_C =	15	A		150 °C	dashed

figure 3. **FWD**

Typical reverse recovered energy loss as a function of collector current

$E_{rec} = f(I_C)$



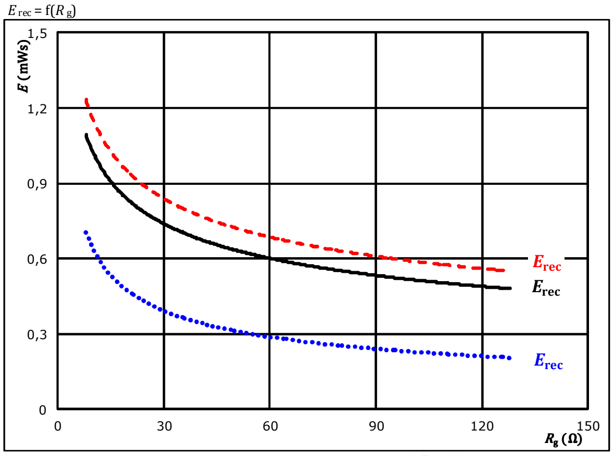
With an inductive load at

V_{CE} =	700	V	T_j:	25 °C	dotted
V_{GE} =	15/0	V		125 °C	solid
R_{gon} =	32	Ω		150 °C	dashed

figure 4. **FWD**

Typical reverse recovered energy loss as a function of gate resistor

$E_{rec} = f(R_g)$



With an inductive load at

V_{CE} =	700	V	T_j:	25 °C	dotted
V_{GE} =	15/0	V		125 °C	solid
I_C =	15	A		150 °C	dashed

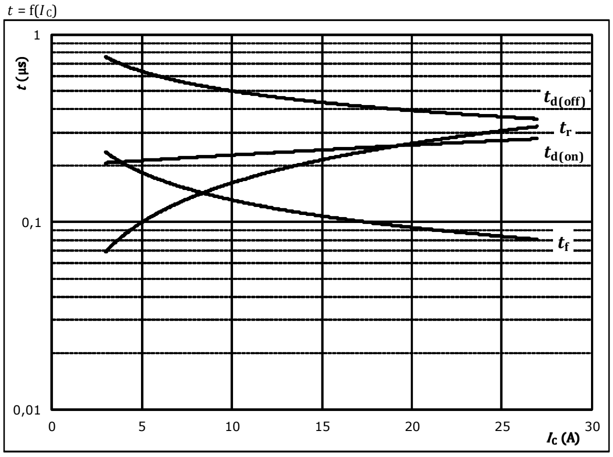
Vincotech

Brake Switching Characteristics

figure 5. **IGBT**

Typical switching times as a function of collector current

$t = f(I_C)$



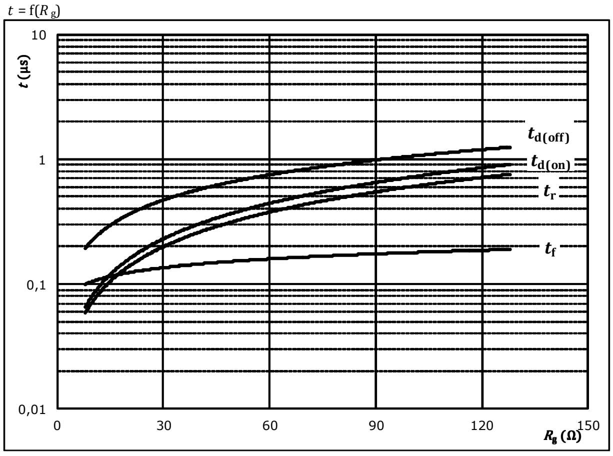
With an inductive load at

T_j =	150	°C
V_{CE} =	700	V
V_{GE} =	15/0	V
R_{gon} =	32	Ω
R_{goff} =	32	Ω

figure 6. **IGBT**

Typical switching times as a function of gate resistor

$t = f(R_g)$



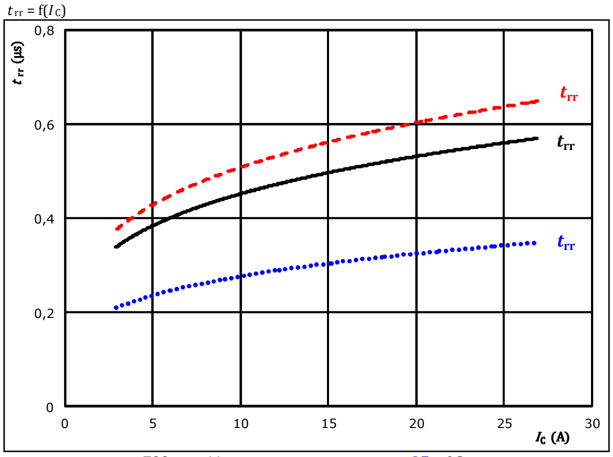
With an inductive load at

T_j =	150	°C
V_{CE} =	700	V
V_{GE} =	15/0	V
I_C =	15	A

figure 7. **FWD**

Typical reverse recovery time as a function of collector current

$t_{rr} = f(I_C)$

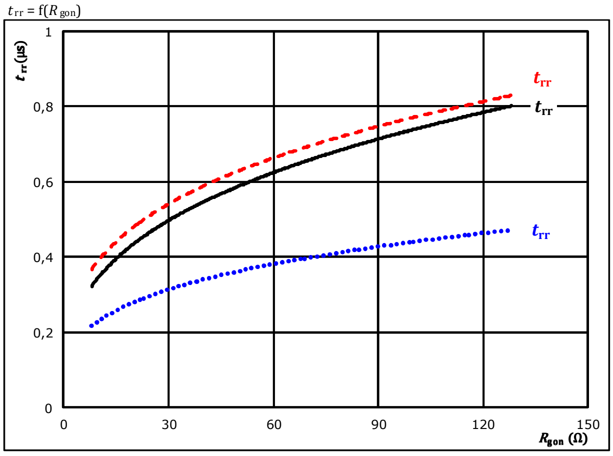


At					
V_{CE} =	700	V		25 °C	dotted
V_{GE} =	15/0	V	T_j:	125 °C	solid
R_{gon} =	32	Ω		150 °C	dashed

figure 8. **FWD**

Typical reverse recovery time as a function of IGBT turn on gate resistor

$t_{rr} = f(R_{gon})$



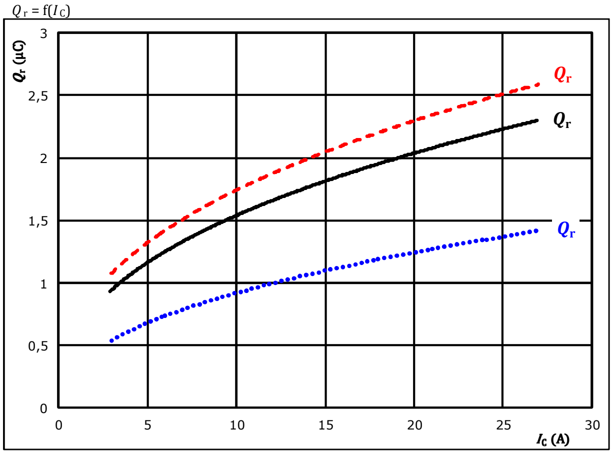
At					
V_{CE} =	700	V		25 °C	dotted
V_{GE} =	15/0	V	T_j:	125 °C	solid
I_C =	15	A		150 °C	dashed

Brake Switching Characteristics

figure 9. **FWD**

Typical recovered charge as a function of collector current

$Q_r = f(I_C)$

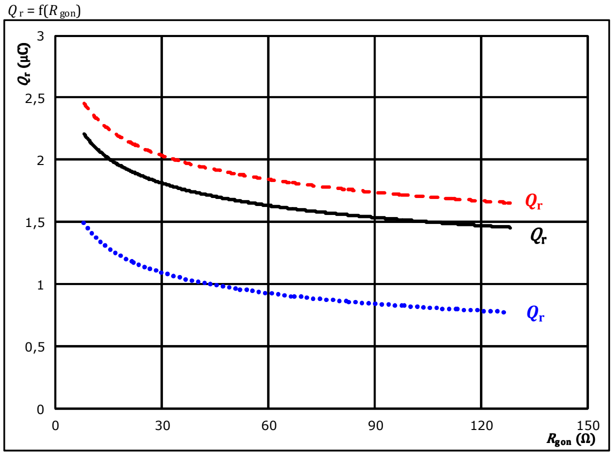


At						
	V_{CE} =	700	V		25 °C	dotted
	V_{GE} =	15/0	V	T_j:	125 °C	solid
	R_{gon} =	32	Ω		150 °C	dashed

figure 10. **FWD**

Typical recovered charge as a function of IGBT turn on gate resistor

$Q_r = f(R_{gon})$

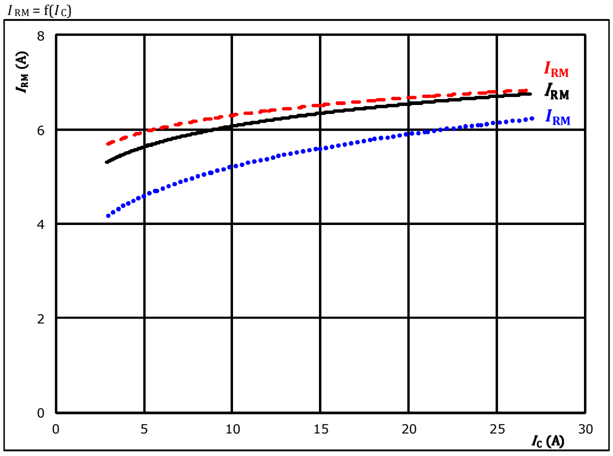


At						
	V_{CE}=	700	V		25 °C	dotted
	V_{GE} =	15/0	V	T_j:	125 °C	solid
	I_C=	15	A		150 °C	dashed

figure 11. **FWD**

Typical peak reverse recovery current current as a function of collector current

$I_{RM} = f(I_C)$

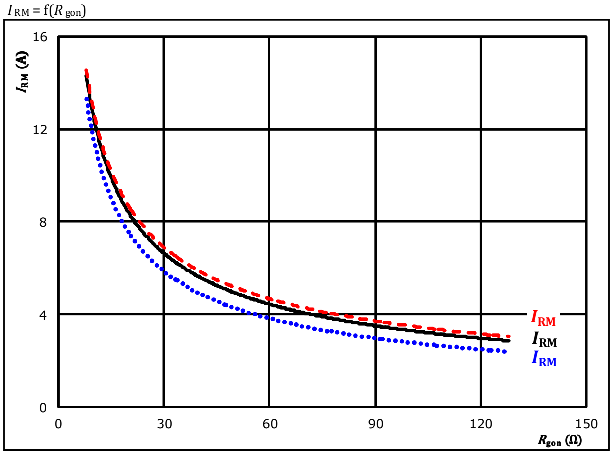


At						
	V_{CE}:	700	V		25 °C	dotted
	V_{GE} =	15/0	V	T_j:	125 °C	solid
	R_{gon} =	32	Ω		150 °C	dashed

figure 12. **FWD**

Typical peak reverse recovery current as a function of IGBT turn on gate resistor

$I_{RM} = f(R_{gon})$



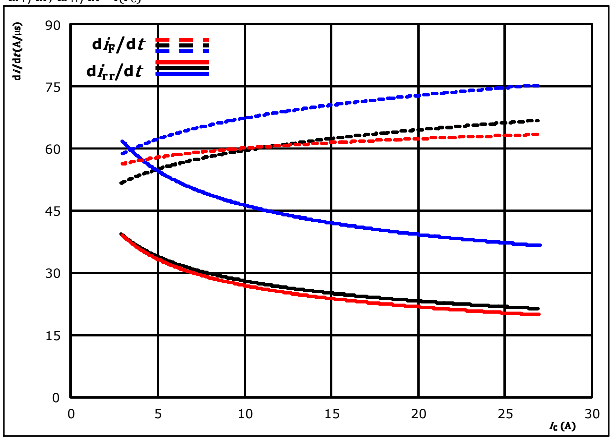
At						
	V_{CE} =	700	V		25 °C	dotted
	V_{GE} =	15/0	V	T_j:	125 °C	solid
	I_C =	15	A		150 °C	dashed

Brake Switching Characteristics

figure 13. **FWD**

Typical rate of fall of forward and reverse recovery current as a function of collector current

di_F/dt, $di_{rr}/dt = f(I_C)$

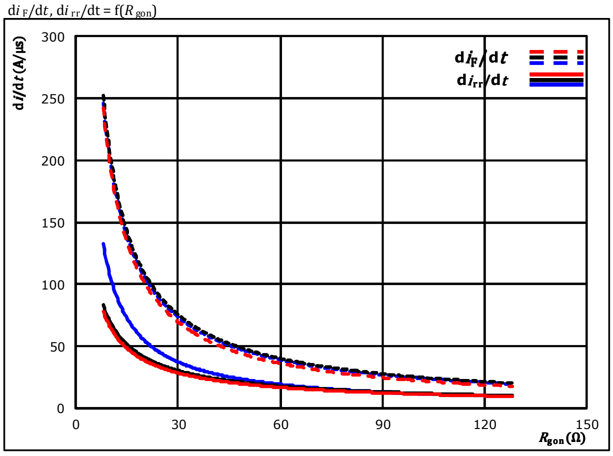


At						
V_{CE} =	700	V		25	°C	···············
V_{GE} =	15/0	V	T_j:	125	°C	———
R_{gon} =	32	Ω		150	°C	– – –

figure 14. **FWD**

Typical rate of fall of forward and reverse recovery current as a function of IGBT turn on gate resistor

di_F/dt, $di_{rr}/dt = f(R_{gon})$

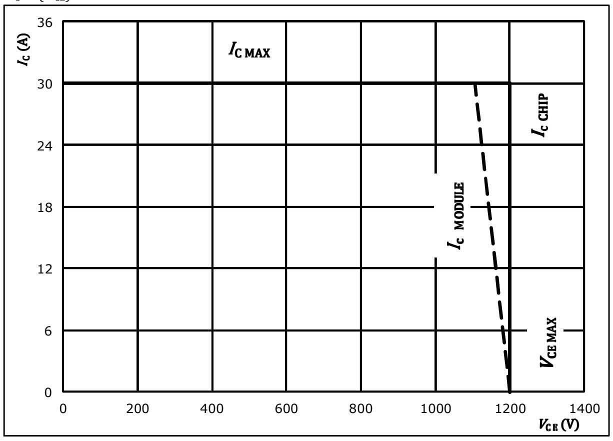


At						
V_{CE} =	700	V		25	°C	···············
V_{GE} =	15/0	V	T_j:	125	°C	———
I_C=	15	A		150	°C	– – –

figure 15. **IGBT**

Reverse bias safe operating area

$I_C = f(V_{CE})$



At		
T_j =	175	°C
R_{gon} =	32	Ω
R_{goff} =	32	Ω

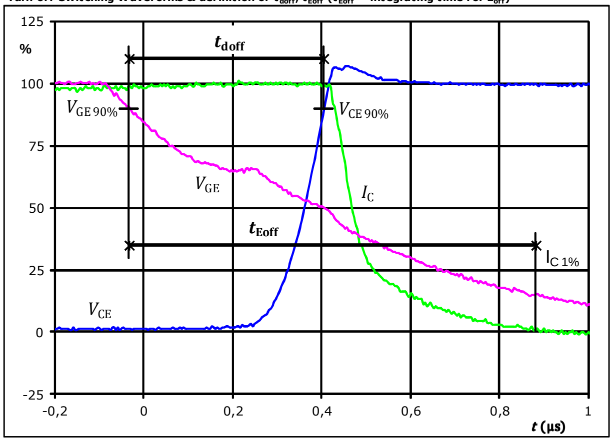
Brake Switching Definitions

General conditions

T_j	=	125 °C
R_{gon}	=	32 Ω
R_{goff}	=	32 Ω

figure 1. IGBT

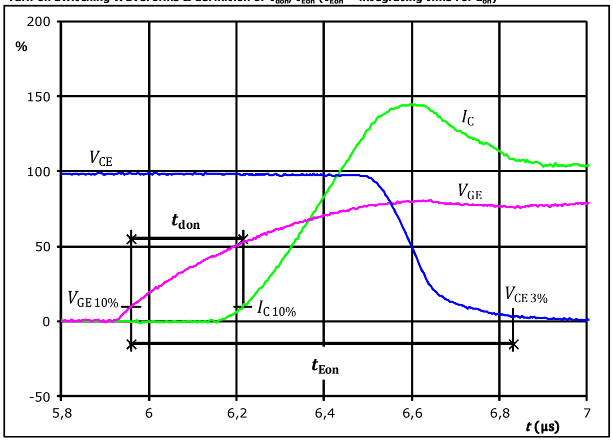
Turn-off Switching Waveforms & definition of t_{doff}, t_{Eoff} (t_{Eoff} = integrating time for E_{off})



$V_{GE}(0\%)$ =	0	V
$V_{GE}(100\%)$ =	15	V
$V_C(100\%)$ =	700	V
$I_C(100\%)$ =	15	A
t_{doff} =	0,442	µs
t_{Eoff} =	0,915	µs

figure 2. IGBT

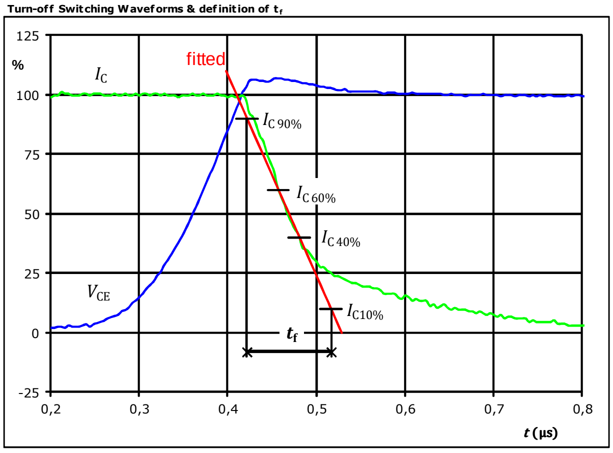
Turn-on Switching Waveforms & definition of t_{don}, t_{Eon} (t_{Eon} = integrating time for E_{on})



$V_{GE}(0\%)$ =	0	V
$V_{GE}(100\%)$ =	15	V
$V_C(100\%)$ =	700	V
$I_C(100\%)$ =	15	A
t_{don} =	0,257	µs
t_{Eon} =	0,872	µs

figure 3. IGBT

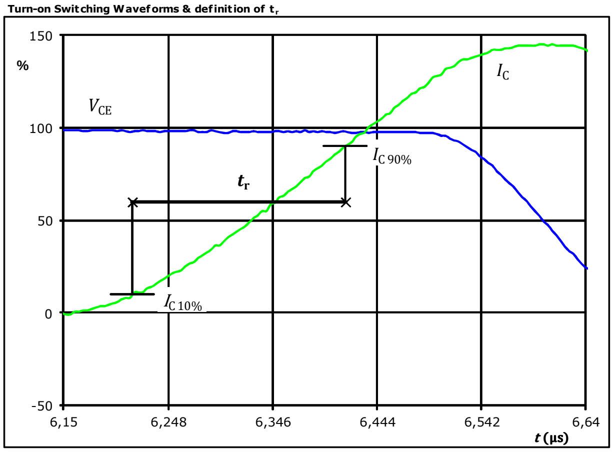
Turn-off Switching Waveforms & definition of t_f



$V_C(100\%)$ =	700	V
$I_C(100\%)$ =	15	A
t_f =	0,088	µs

figure 4. IGBT

Turn-on Switching Waveforms & definition of t_r

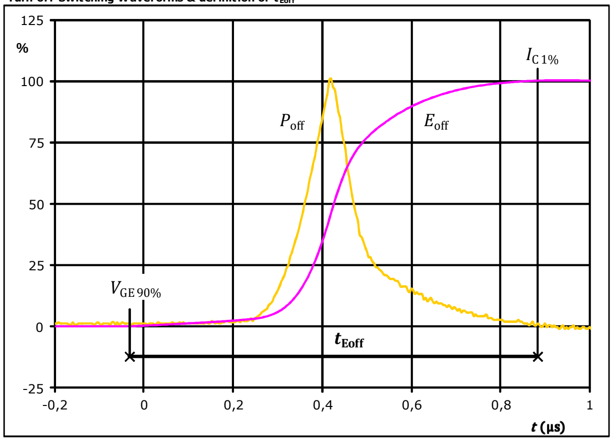


$V_C(100\%)$ =	700	V
$I_C(100\%)$ =	15	A
t_r =	0,200	µs

Brake Switching Characteristics

figure 5. **IGBT**

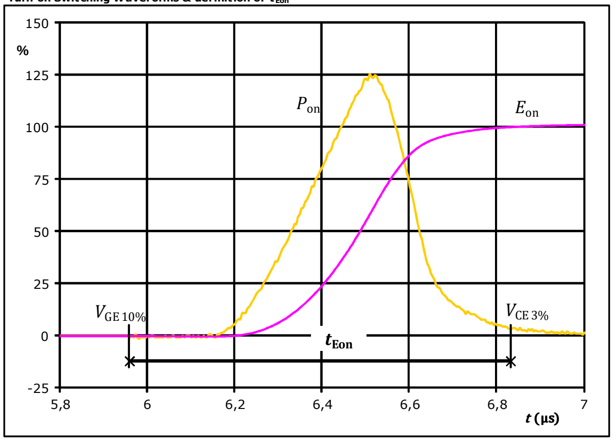
Turn-off Switching Waveforms & definition of t_{Eoff}



P_{off} (100%) =	10,55	kW
E_{off} (100%) =	1,71	mJ
t_{Eoff} =	0,92	µs

figure 6. **IGBT**

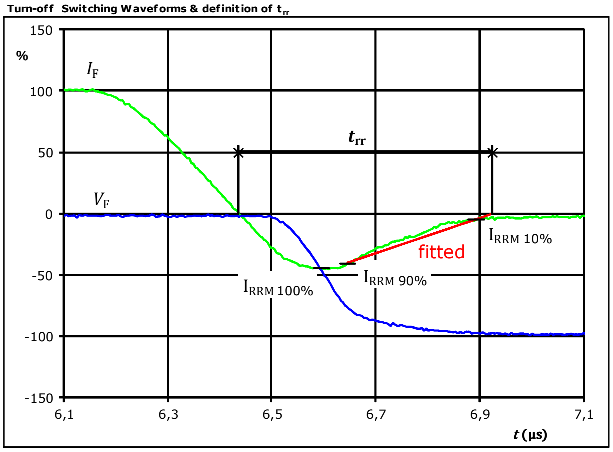
Turn-on Switching Waveforms & definition of t_{Eon}



P_{on} (100%) =	10,55	kW
E_{on} (100%) =	3,57	mJ
t_{Eon} =	0,87	µs

figure 7. **FWD**

Turn-off Switching Waveforms & definition of t_{rr}

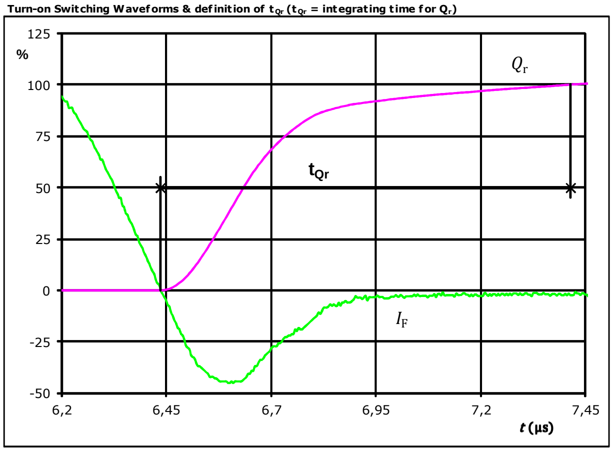


V_F (100%) =	700	V
I_F (100%) =	15	A
I_{RRM} (100%) =	-7	A
t_{rr} =	0,485	µs

Brake Switching Characteristics

figure 8. **FWD**

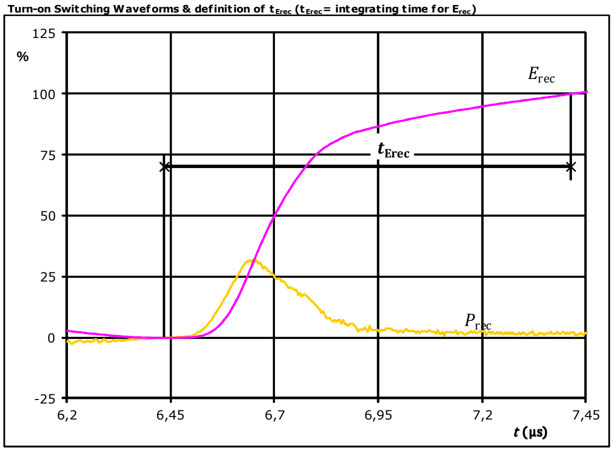
Turn-on Switching Waveforms & definition of t_{Qr} (t_{Qr} = integrating time for Q_r)



I_F (100%) =	15	A
Q_r (100%) =	1,88	µC
t_{Qr} =	0,98	µs

figure 9. **FWD**

Turn-on Switching Waveforms & definition of t_{Erec} (t_{Erec}= integrating time for E_{rec})



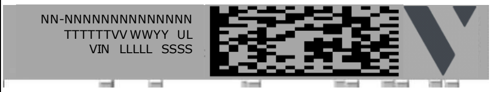
P_{rec} (100%) =	10,55	kW
E_{rec} (100%) =	0,78	mJ
t_{Erec} =	0,98	µs

Vincotech

10-FY12PMA025M7-P588A78
10-PY12PMA025M7-P588A78Y
10-F112PMA025M7-P588A79
datasheet

Ordering Code & Marking

Version	Ordering Code
without thermal paste 12 mm housing with solder pins	10-FY12PMA025M7-P588A78
with thermal paste 12 mm housing with press-fit pins	10-PY12PMA025M7-P588A78Y-/3/
without thermal paste 17 mm housing with solder pins	10-F112PMA025M7-P588A79

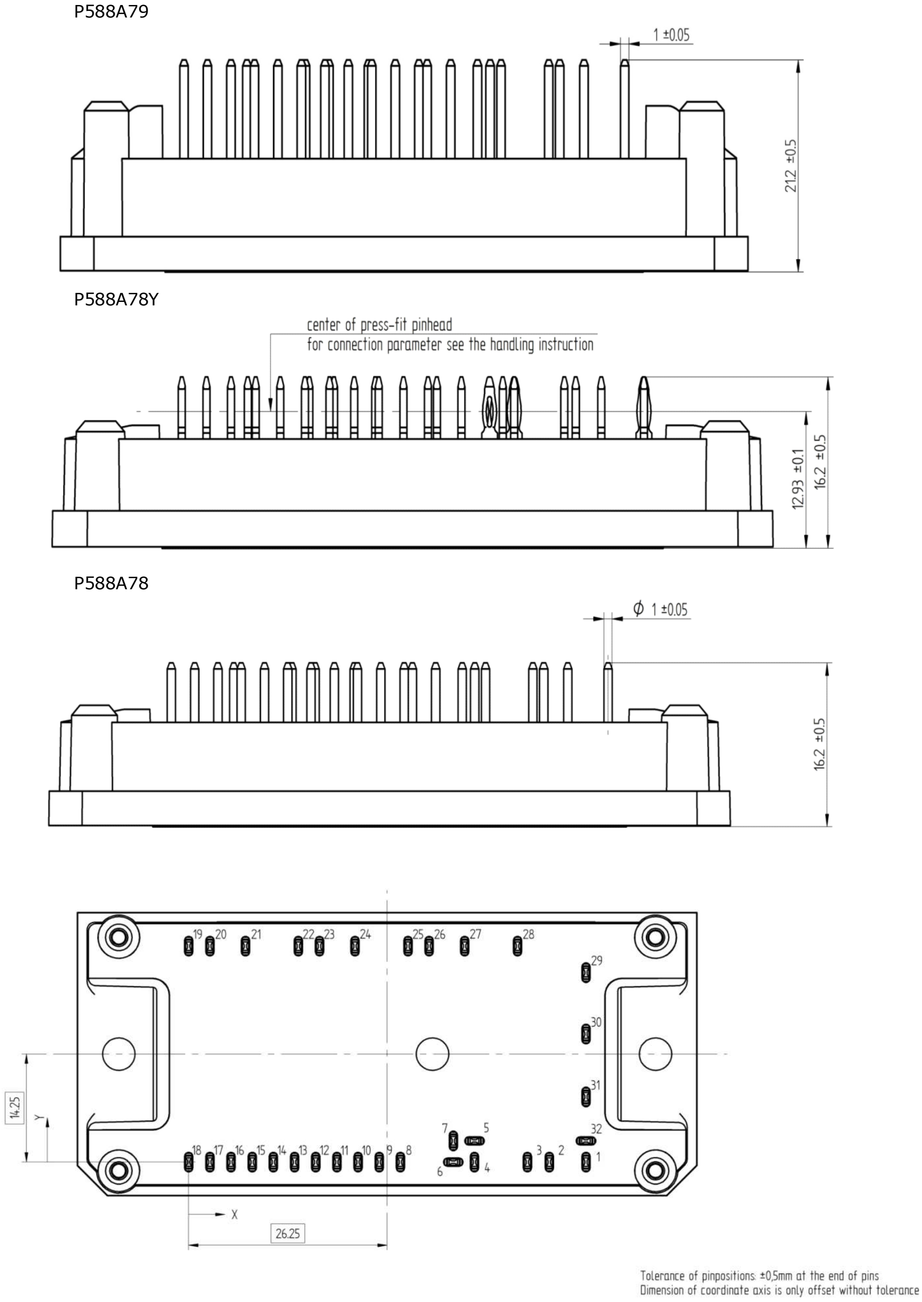


Text	Name		Date code	UL & VIN	Lot	Serial
	NN-NNNNNNNNNNNNNN-TTTTTTVV		WWYY	UL VIN	LLLLL	SSSS
Datamatrix	Type&Ver	Lot number	Serial	Date code		
	TTTTTTTVV	LLLLL	SSSS	WWYY		

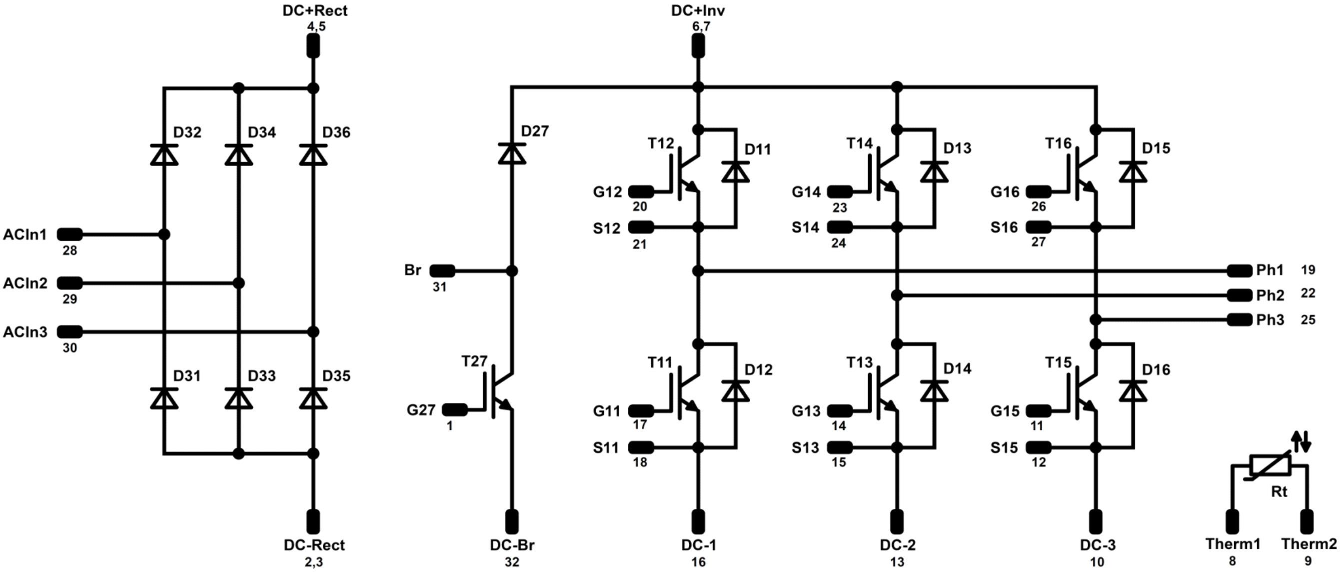
Outline

Pin table

Pin	X	Y	Function
1	52,55	0	G27
2	47,7	0	DC-Rect
3	44,8	0	DC-Rect
4	37,8	0	DC+Rect
5	37,8	2,8	DC+Rect
6	35	0	DC+Inv
7	35	2,8	DC+Inv
8	28	0	Therm1
9	25,2	0	Therm2
10	22,4	0	DC-3
11	19,6	0	G15
12	16,8	0	S15
13	14	0	DC-2
14	11,2	0	G13
15	8,4	0	S13
16	5,6	0	DC-1
17	2,8	0	G11
18	0	0	S11
19	0	28,5	Ph1
20	2,8	28,5	G12
21	7,5	28,5	S12
22	14,5	28,5	Ph2
23	17,3	28,5	G14
24	22	28,5	S14
25	29	28,5	Ph3
26	31,8	28,5	G16
27	36,5	28,5	S16
28	43,5	28,5	ACIn1
29	52,55	25	ACIn2
30	52,55	16,9	ACIn3
31	52,55	8,6	Br
32	52,55	2,8	DC-Br



Pinout



Identification

ID	Component	Voltage	Current	Function	Comment
D31, D32, D33, D34, D35, D36	Rectifier	1600 V	35 A	Rectifier Diode	
T11, T12, T13, T14, T15, T16	IGBT	1200 V	25 A	Inverter Switch	
D11, D12, D13, D14, D15, D16	FWD	1200 V	25 A	Inverter Diode	
T27	IGBT	1200 V	15 A	Brake Switch	
D27	FWD	1200 V	10 A	Brake Diode	
Rt	NTC			Thermistor	

Packaging instruction				
Standard packaging quantity (SPQ) 100	>SPQ	Standard	<SPQ	Sample

Handling instruction
Handling instructions for *flow* 1 packages see vincotech.com website.

Package data
Package data for *flow* 1 packages see vincotech.com website.

UL recognition and file number
This device is certified according to UL 1557 standard, UL file number E192116. For more information see vincotech.com website.

Document No.:	Date:	Modification:	Pages
10-xY12PMA025M7-P588A7xx-D2-14	14 Feb. 2018		